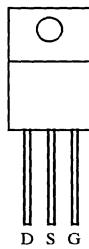


**Product Summary**

V <sub>DS</sub> (V)	r <sub>DS(on)</sub> (Ω)	I <sub>D</sub> (A)
500	0.515	12

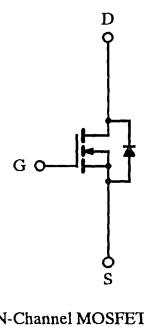
Parametric limits in accordance with MIL-S-19500/592 where applicable.

TO-254AA  
Hermetic Package



Case Isolated

Top View

**Absolute Maximum Ratings (T<sub>C</sub> = 25°C Unless Otherwise Noted)**

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V <sub>DS</sub>	500	V
Gate-Source Voltage	V <sub>GS</sub>	±20	
Continuous Drain Current (T <sub>J</sub> = 150°C)	I <sub>D</sub>	12	A
		8	
Pulsed Drain Current	I <sub>DM</sub>	48	
Avalanche Current	I <sub>AR</sub>	12	
Maximum Power Dissipation	P <sub>D</sub>	150	W
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>sig</sub>	-55 to 150	°C

**Thermal Resistance Ratings**

Parameter	Symbol	Limit	Unit
Maximum Junction-to-Case	R <sub>thJC</sub>	0.83	°C/W

Specifications ( $T_J = 25^\circ\text{C}$  Unless Otherwise Noted)

Parameter	Symbol	Test Condition	Limit			Unit
			Min	Typ <sup>a</sup>	Max	
<b>Static</b>						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{GS} = 0 \text{ V}, I_D = 1000 \mu\text{A}$	500			
Gate Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}, I_D = 250 \mu\text{A}, T_J = -55^\circ\text{C}$			5.0	V
		$V_{DS} = V_{GS}, I_D = 250 \mu\text{A}, T_J = 25^\circ\text{C}$	2.0		4.0	
		$V_{DS} = V_{GS}, I_D = 250 \mu\text{A}, T_J = 125^\circ\text{C}$	1.0			
Gate-Body Leakage	$I_{GSS}$	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			$\pm 100$	nA
		$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}, T_J = 125^\circ\text{C}$			$\pm 200$	
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 400 \text{ V}, V_{GS} = 0 \text{ V}$			25	$\mu\text{A}$
		$V_{DS} = 400 \text{ V}, V_{GS} = 0 \text{ V}, T_J = 125^\circ\text{C}$			250	
		$V_{DS} = 500 \text{ V}, V_{GS} = 0 \text{ V}, T_J = 125^\circ\text{C}$			1000	
Drain-Source On-State Resistance <sup>b</sup>	$r_{DS(\text{on})}$	$V_{GS} = 10 \text{ V}, I_D = 12 \text{ A}$			0.515	$\Omega$
		$V_{GS} = 10 \text{ V}, I_D = 8 \text{ A}, T_J = 125^\circ\text{C}$			0.9	
<b>Dynamic</b>						
Total Gate Charge <sup>c</sup>	$Q_g$	$V_{DS} = 250 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 12 \text{ A}$	55		120	nC
Gate-Source Charge <sup>c</sup>	$Q_{gs}$		5		19	
Gate-Drain Charge <sup>c</sup>	$Q_{gd}$		27		70	
Turn-On Delay Time <sup>c</sup>	$t_{d(\text{on})}$	$V_{DD} = 250 \text{ V}, R_L = 20.8 \Omega$ $I_D \cong 12 \text{ A}, V_{GEN} = 10 \text{ V}, R_G = 2.35 \Omega$			35	ns
Rise Time <sup>c</sup>	$t_r$				190	
Turn-Off Delay Time <sup>c</sup>	$t_{d(\text{off})}$				170	
Fall Time <sup>c</sup>	$t_f$				130	
<b>Source-Drain Diode Ratings and Characteristics</b>						
Continuous Current	$I_S$				12	A
Pulsed Current	$I_{SM}$				48	
Diode Forward Voltage <sup>b</sup>	$V_{SD}$	$I_F = 12 \text{ A}, V_{GS} = 0 \text{ V}$			1.7	V
Reverse Recovery Time	$t_{rr}$	$I_F = 12 \text{ A}, dI/dt = 100 \text{ A}/\mu\text{s}$			1600	ns

## Notes:

- a. For design aid only; not subject to production testing.
- b. Pulse test; pulse width  $\leq 300 \mu\text{s}$ , duty cycle  $\leq 2\%$ .
- c. Independent of operating temperature.